



# 200G QSFP56 to 2X100G QSFP56 Passive Direct Attach Copper Cables FWH2H-200xxxxC

# Features

- QSFP56 conforms to the Small Form Factor SFF8636
- 4-Channel QSFP56 2X breakout passive copper cable assembly
- Maximum aggregate data rate: 200Gb/s
- I2C interface for EEPROM signature which can be customized and CMIS V4.0 complianted
- Operating Temperature: 0~70°C
- ROHS Compliant and lead free

# **Applications**

- 40GE/100GE/200GE
- Infiniband QDR/FDR/EDR/HDR
- Data storage and communication industry
- Switch / router / HBA
- Enterprise network
- Data Center Network

# STANDARDS COMPLIANCE

- IEEE 802.3bj&IEEE802.3cd
- 100GEBASE-CR4&200GBASE-CR4
- InfiniBand architecture

# **Product Description**

FIBERSTAMP's FWH2H-200xxxxxC cable assembly is high performance, cost effective I/O solutions for LAN, HPC and SAN, it is used in 2\*100 gigabit Ethernet links over copper cable which provides connectivity between system units with a QSFP56 on one side and two QSFP56 on the other side. The high speed cable assembly meets and exceeds 200 Gigabit Ethernet, InfiniBand



EDR /HDR and temperature requirements for performance and reliability.

### **Recommended Operating Conditions**

Parameter	Symbol	Min	Typical	Max	Unit
Storage Ambient Temperature		-40		+85	°C
Operating Case Temperature	Тс	0		+70	°C
Power Supply Voltage	V <sub>CC3</sub>	3.14	3.3	3.47	V



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Data Rate Per Lane		1		28	GBaud/s
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# **Differential Impedance**

Parameter	Symbol	Min	Typical	Max	Unit
Differential Impedance(bulk cable)	Rin1,P-P	95	100	110	Ω
Differential Impedance (Mated connector)	Rin2,P-P	90	100	110	Ω
Differential Impedance(cable termination)	Rin3,P-P	85	100	110	Ω

# PCB Contact Configuration

38	GND		GND	1
37	TX1n		TX2n	
36	TX1p		TX2p	2
35	GND	- 7	GND	5
34	TX3n			4
33	TX3p		TX4n	5
32	GND		TX4p	0
31	LPMode	Card	GND	2 3 5 6 7 9 10 10
30	Vcc1	<u>n</u>	ModSe	91L 0
29	VccTx	d	ResetL	. 9
28	IntL	ш	VccRx	
27	ModPrsL	Edge	SCL	11
26	GND	Q	SDA	12
25	RX4p	U U	GND	13
24	RX4n		RX3p	14
23	GND	10	RX3n	15
22	RX2p		GND	16
21	RX2n		RX1p	17
20	GND	1	RX1n	18
77			GND	19

# ELECTRICAL

Item	Specification
Low Level Contact Resistance	Initial: Baseline, with 75mm cable from the backshell edge. Change : 20 milliohms maximum
Insulation Resistance (Raw cable)	100VDC, 1000Mohm (Min.)
Dielectric Withstanding Voltage	AC 300V 1min, no breakdown or flash

A	Time domain parameter	Test condition	SPEC		Equipment
1	Differential Impedance(bulk cable)		100+10/-50hms		
2	Differential Impedance (Mated		100+10/-10ohms		
	connector)				55071.0
3	Differential Impedance(cable	TDR Tr:25ps	100+10/-15ohms		E5071C or DSA8300
Ū	termination)				D3A6300
4	Intra-skew		L*15+20	L:length(m)	
4	4 InitG-skew	ining-skew		SPEC:ps	



Data Sheet

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Data Sheet

В	Frequency domain parameter	Test condition	Test spec(dB)	f(GHz)	
1	SDD11/SD D22	Freq:50MHz ~20GHz Points:1601	-22+20/25.78*f*10^(-3) -10.66+14*log((f*10^(-3))/5.5 ) ≤5.3dB@13.26GHz	0.05≤f<4.1 4.1≤f≤19	
2	SCC11/SC C22	Freq:50MHz ~20GHz Points:1601	≤-2dB	0.2≤f≤19	
3	SDC11/SD C22	Freq:50MHz ~20GHz Points:1601	-16+2*f/3	0.05≤f≤2	
4	SCD21-SDD21	Freq:50MHz ~20GHz Points:1601	10 as 0.01≤f < 12.89 -27+29/22*f*0.001 a s 12.89≤f < 15.7 6.3 as 15.7≤f≤19	0.01≤f≤19	E5071C
5	MDNEXT	Freq:50MHz ~20GHz Points:1601	≤-26dB@12.89GHz	0.01≤f≤19	
6	SDD21	Freq:50MHz ~20GHz Points:1601 IF: 1KHz	-0.7*(f*10^(-3))^0.5-0.3*(f*10 ^(-3))- 0.01*(f*10^(-3))^2 <17.16dB@13.26GHz	0.01≤f≤19	
7	СОМ	IEEE802.3cd	>3dB		

# MECHANICAL

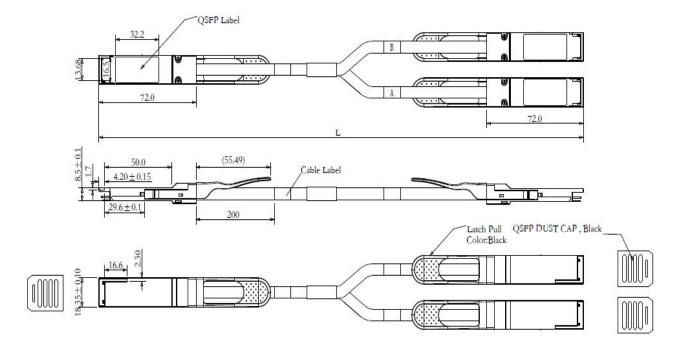
Item	Specification
Mating Force	40N Max. With retention latch disengaged.
Un-mating Force	30N Max. With retention latch disengaged.
Latch retention force	90N Min.
Durability	250 cycles





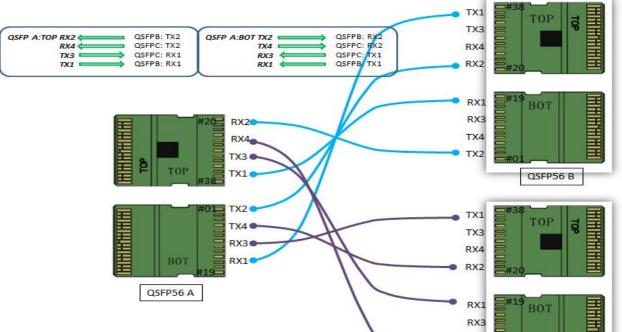


# **Mechanical Dimensions**



	L (m)	Tolerance (cm)	Туре	Cable Dia. (mm)	Dynamic (mm)	Static (mm)	Assembly Min Bend Radius(mm)
1. Martin	0.5≤L<3	±5	30AWG	6.9± 0.3	72	36	63
Bill Ball Ballins	3≪L≪5	± <mark>8</mark>	26AWG	8.4± 0.3	90	45	7 <mark>4</mark>
Min 90° Assembly Bend Radius		į.					

# Wiring connection diagram





### **ENVIRONMENTAL**

Item	Specification
Physical shock	Subject mated specimens to 30G's half-sine shock pulses of 11 milliseconds duration. 3
	shocks in each direction applied along 3 mutually perpendicular planes, 18 total



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Item	Specification
	shocks
Vibration (random)	Subject mated specimens to 3.10G's rms between 20-500
Vibration (random)	Hz for 15 minutes in each of 3 mutually perpendicular planes
Thermal shock	100 cycles of:
	a) -55°C for 30 minutes b) +85°C for 30 minutes
Temperature Life	Subject mated Specimens to +105°C for 500 hours
Humidity and Temperature cycling	Subject unmated specimens to 10 cycles (10 days)
nomially and temperature cycling	between 25 and 65℃at 80% to 100% RH
Visual Examination.	Connectors & contacts shall have no evidence of physical defects or otherwise unfit
	for testing.

# **Regulatory Compliance**

FIBERSTAMP FWH2H-200xxxxxC passive cable assembly meets the requirements of the following standards:

Feature	Standard		
	EN 62368-1: 2014		
Electrical Safety	IEC 62368-1:2014		
	UL 62368-1:2014		
Environmental protection	Directive 2011/65/EU with amendment(EU)2015/863		
	EN55032: 2015		
CE EMC	EN55035: 2017		
	EN61000-3-2:2014		
	EN61000-3-3:2013		
FCC	FCC Part 15, Subpart B; ANSI C63.4-2014		

# Ordering information

Part Number	FWH2H-200xxxxxC		
Length (meter)	1	2	3
Wire gauge (AWG)	30	30	26

# **Important Notice**

Performance figures, data and any illustrative material provided in this data sheet are typical and must be specifically

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